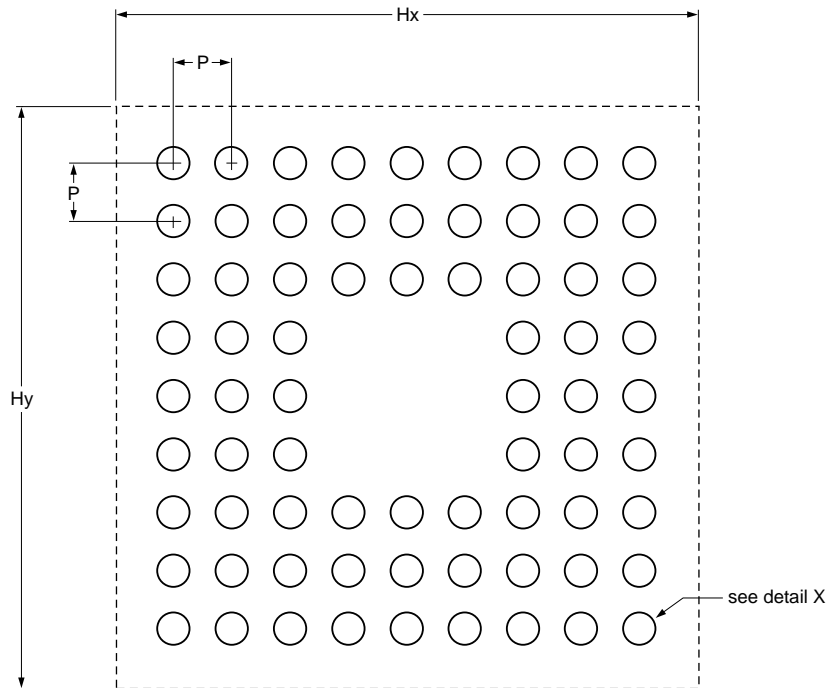





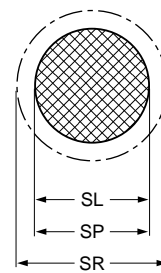
Footprint information for reflow soldering of TFBGA180 package

SOT570-2



Generic footprint pattern
Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area
- solder resist



detail X

DIMENSIONS in mm

P	SL	SP	SR	Hx	Hy
0.80	0.400	0.400	0.550	12.575	12.575